

Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Please cancel claims 1-65 without prejudice or disclaimer.

Please add the following new claims:

66. (New) A semiconductor device comprising:

a semiconductor chip;

first and second radiation members thermally and electrically connected to the semiconductor chip interposed therebetween, and having a radiation surface for radiating heat from the semiconductor chip; and

bump shaped bonding members formed on a surface of one of the first and second radiation members; and

a Resist Assist Bonding resin disposed in spaces between the bump shaped bonding members.

67. (New) The semiconductor device of claim 66, wherein the first and second radiation members are made of metallic material that is superior to tungsten and molybdenum in at least one of an electrical conductivity and a thermal conductivity.